

H252-Z12

High Density Server - UP 2U 4 Nodes Server



Features

- 2U - 4 nodes rear access server system
- Single AMD EPYC™ 7003 Series processors
- 8-Channel RDIMM/LRDIMM DDR4, 32 x DIMMs
- 8 x 1Gb/s LAN ports (Intel® I350-AM2)
- 4 x Dedicated management ports
- 1 x CMC global management port
- 12 x SATA hot-swappable HDD/SSD bays
- 8 x M.2 with PCIe Gen3 x4 interface
- 8 x Low profile PCIe x16 expansion slots
- 4 x OCP 2.0 Gen3 x16 mezzanine slots
- Aspeed® AST2500 remote management controller
- 2+0 1600W (240V) 80 PLUS Platinum power supply

Specification

Dimensions	2U 4 Nodes - Rear access (W440 x H87.5 x D695 mm)	Backplane I/O	12 x ports Speed and bandwidth: SATA 6Gb/s per port
Motherboard	MZ12-HD0 Rev. 3.0	TPM	1 x TPM header with SPI interface Optional TPM2.0 kit: CTM010
CPU	AMD EPYC™ 7003 Series processors Single processor, 7nm technology, cTDP up to 240W Up to 64-core, 128 threads per processor, total 4 x Socket SP3 TDP up to 225W, cTDP up to 240W, Conditional support 280W Compatible with AMD EPYC™ 7002 Series processors	Power Supply	2+0 1600W (240V) 80 PLUS Platinum power supply
Chipset	System on Chip	System Management	Aspeed® AST2500 management controller GIGABYTE Management Console (AMI MegaRAC SP-X)
Memory	8-Channel DDR4 memory, total 32 x DIMM slots RDIMM/LRDIMM modules up to 128GB supported Memory speed: Up to 3200 MHz	OS Compatibility	Windows Server 2016 / 2019 RHEL 8.3 (x64) or later SLES 12 SP5 (x64) / 15 SP2 (x64) or later Ubuntu 18.04.5 LTS (x64) / 20.04 LTS (x64) or later VMware ESXi 6.7 Update3 P03 / 7.0 Update1 or later Citrix Hypervisor 8.2.0 or later
LAN	8 x 1GbE LAN ports (1 x Intel® I350-AM2) 4 x Dedicated management ports 1 x 10/100/1000 CMC global management port	Weight	Net Weight: 27.3 kg Gross Weight: 45.92 kg
Video	Integrated in Aspeed® AST2500 2D Video Graphic Adapter with PCIe bus interface 1920x1200@60Hz 32bpp, DDR4 SDRAM	System Fans	4 x 80x80x38mm (16,300rpm)
Storage	12 x 3.5" SATA hot-swappable HDD/SSD bays	Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
Expansion Slots	4 x Low profile half-length slots with PCIe x16 (Gen4 x16) 4 x Low profile half-length slots with PCIe x16 (Gen3 x16) 4 x OCP 2.0 mezzanine slot with PCIe Gen3 x16 bandwidth 8 x M.2 slots (PCIe Gen3 x4, M-key)	Packaging Content	1 x H252-Z12 4 x CPU heatsinks 1 x Rail kit
Internal I/O	Per node: 2 x M.2 slots, 1 x USB 3.0 header, 1 x TPM header, 1 x OCP 2.0 mezzanine slots, 1 x Front panel header, 1 x Back plane board header, 1 x IPMB connector, 1 x Clear CMOS jumper, 1 x BIOS recovery jumper	Reference Numbers	Barebone package: 6NH252Z12MR-00 Rev. A00 Spare parts: - Motherboard: 9MZ12HD0NR-00 Rev. 3.0 - Rail kit: 25HB2-AN6103-K0R - CPU heatsink: 25ST1-44320J-A0R - Back plane board: 9CBPH0C3NR-00 - Power Supply: 25EP0-216008-L0S - Ring topology kit: 6NH262Z65SR-00-100 (optional extra)
Front I/O	-		
Rear I/O	Total: 8 x USB 3.0, 4 x VGA, 8 x RJ45, 4 x MLAN, 1 x CMC LAN		

* All specifications are subject to change without notice. Please visit our website for the latest information.

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